### 505734752 10/22/2019

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5781566

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
FUMITAKA SUGAYA	08/13/2019

#### **RECEIVING PARTY DATA**

Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION
Street Address:	4-14-1 ASAHI-CHO
Internal Address:	ATSUGI-SHI
City:	KANAGAWA
State/Country:	JAPAN
Postal Code:	2430014

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16485894

#### **CORRESPONDENCE DATA**

**Fax Number:** (312)803-4960

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: CHIP LAW GROUP

Address Line 1: 505 N LAKESHORE DR

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Address Line 4: CHICAGO, ILLINOIS 60611

ATTORNEY DOCKET NUMBER:	SP368307US00
NAME OF SUBMITTER:	PRAMOD CHINTALAPOODI
SIGNATURE:	/Pramod Chintalapoodi/
DATE SIGNED:	10/22/2019

**Total Attachments: 1** 

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PATENT 505734752 REEL: 050790 FRAME: 0370

Attorney Docket No.: Sony Ref. No.: SP368307US00

# DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	STORAGE DEVICE
As the below	named inventor, I hereby declare that:
This declarati	The established confliction are
	United States application or PCT international application number PCT/JP2018/003568 filed on 2018/02/02
The above-id	entified application was made or authorized to be made by me.
I believe that WHEREAS.	I am the original inventor or an original joint inventor of a claimed invention in the application.  SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at
4-14-1 A	sahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of
	interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar on which may be granted therefor in the United States and in any and all foreign countries;
of which are legal represer in and to any any and all pr Convention F adheres, and United States	EFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and natives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to riority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters (ASSIGNEE, as the assignce of the whole right, title and interest thereto;
designee, as remuneration	r agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of ates and countries foreign thereto;
application fo	r agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for or foreign patents, for filting subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters may be granted for my aforesaid invention, as said ASSIGNEE thereof shall bereafter require and prepare at its own expense;
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;	
And I hereby this assignme	covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with out and sale.
	nowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of a five (5) years, or both.
LEGAL NA	ME OF INVENTOR
Inventor:	FUMITAKA SUGAYA Date: 2019 - 8 - 13
Signature:	Fumitaka Gugayo

**RECORDED: 10/22/2019** 

PATENT REEL: 050790 FRAME: 0371